

ROLLING CONTACT SCREENING METHOD AND APPARATUS

Abstract

A method of applying paste to an electronic circuit board substrate containing via openings comprises providing over the substrate a mask having openings therein for lines and openings corresponding to the substrate via openings, and providing a roller having a surface adjacent the roller. Paste is then applied either to the mask or to a side of the surface facing the mask. The method then includes rolling the roller and the surface over the mask and flowing the paste into the openings in the mask without substantially sliding the roller and surface over the mask. In the preferred embodiment, paste is applied to a side of the surface facing the mask and the surface containing the paste is rolled over the mask. The surface may be attached to the roller. More preferably, the surface is on a film strip, separate from the roller, disposed between the roller and the substrate.